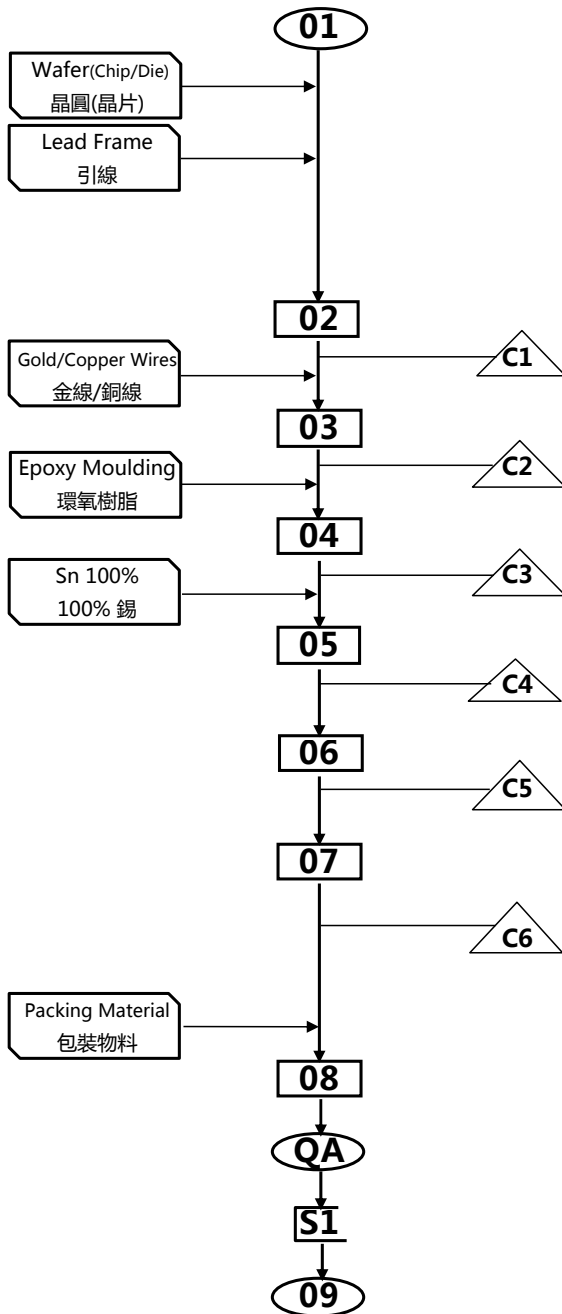


DIODES / TRANSISTORS DIE BONDING 二極管、三極管固晶

PROCESS FLOW CHART FOR EUTECTIC WIRE BONDING PROCESS PRODUCTS
共晶焊線工藝產品工序流程圖 (SOT23, SOD323)



PROCESS DESCRIPTION

流程說明：

01	MATERIAL INCOMING INSPECTION 來料檢查
02	EUTECTIC DIE BONDING 共晶固晶 (晶片焊接)
03	WIRE BONDING 引線鍵合 (焊線焊接)
04	MOULDING & TRIMMING 注塑及修剪水口
05	SURFACE FABRICATION 表面加工
06	CUTTING & FORMING 切割及成型
07	100% ELECTRICAL TESTING, LASER MARKING & TAPING 100% 電性測試、激光法標記及上帶
08	PACKING 包裝
09	FINAL INSPECTION BEFORE DISPATCHING 交貨前最終檢查
QA	QUALITY ASSURANCE 品質保證檢查
S1	STORAGE 倉儲
C1	QUALITY MONITORING AND CONTROL(IPQC) OF DIE BONDING 晶片焊接過程品質監測及控制
C2	QUALITY MONITORING AND CONTROL(IPQC) OF WIRE BONDING 焊線焊接過程品質監測及控制
C3	QUALITY MONITORING AND CONTROL(IPQC) OF MOULDING 注塑過程品質監測及控制
C4	QUALITY INSPECTION AND CONTROL OF SURFACE FABRICATION 表面加工品質檢查及控制
C5	QUALITY MONITORING AND CONTROL(IPQC) OF CUTTING & FORMING 切割及成型過程品質監測及控制
C6	QUALITY MONITORING AND CONTROL(IPQC) OF TESTING, MARKING & TAPING 測試、標記及上帶過程品質監測及控制

	Operation 操作		Inspection 檢查
	Storage 儲存		Material 材料
	Quality Monitoring and Control 品質監測及控制		Outsourcing Process 外包工序